



Clean Version of Amended Specification Paragraph

Title: SELECTIVE DEPOSITION OF SOLDER BALL CONTACTS

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The paragraph beginning on page 11, line 9.

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A still further embodiment is described with reference to Figures 4(A)-4(M) and 6(A)-6(C). In this embodiment, processing proceeds to the etching of through holes 180 to metal contact pads 150 as shown in Figure 4(M). Instead of removing the resist at this stage, a layer of lead 225 is applied to the exposed portions of metal contact pads 150 through electrolysis. A layer of tin 230 is then formed on the layer of lead 225. The lead layer 225 is preferably approximately 0.91 microns deep. The tin layer 230 is preferably approximately 1.42 microns deep. The lead layer 225 and the tin layer 230 collectively form the solder contacts 200 as shown in Figure 6(A). Other metallurgies may be substituted for the lead/tin combination, and the deposition may include more than two layers.
